

## **Notification about the transfer of the semiconductor business**

The semiconductor business of Panasonic Corporation was transferred on September 1, 2020 to Nuvoton Technology Corporation (hereinafter referred to as "Nuvoton"). Accordingly, Panasonic Semiconductor Solutions Co., Ltd. became under the umbrella of the Nuvoton Group, with the new name of Nuvoton Technology Corporation Japan (hereinafter referred to as "NTCJ").

In accordance with this transfer, semiconductor products will be handled as NTCJ-made products after September 1, 2020. However, such products will be continuously sold through Panasonic Corporation.

Publisher of this Document is NTCJ.

If you would find description "Panasonic" or "Panasonic semiconductor solutions", please replace it with NTCJ.

※ Except below description page

"Request for your special attention and precautions in using the technical information and semiconductors described in this book"

Nuvoton Technology Corporation Japan

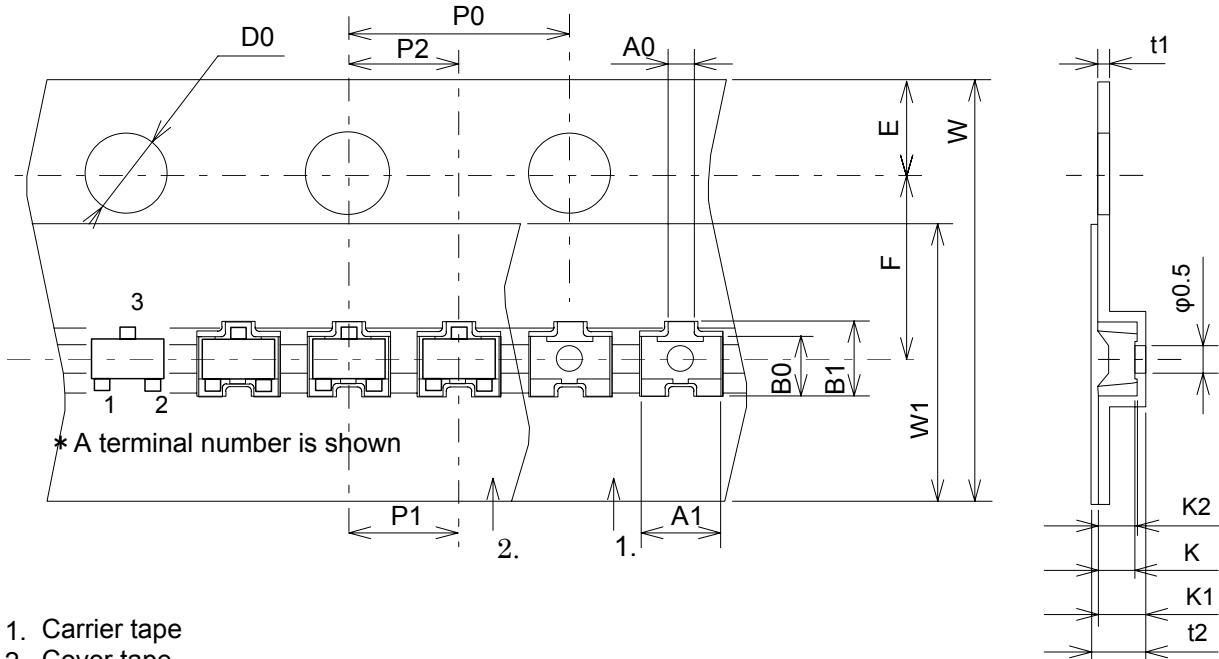
<b>Reference</b>	<b>Tape and reel information</b>	<b>SSSMini3-F2-B</b>	
		Total pages	page
		2	1

1. Taping quantity

The standard quantity shall be 10000 pcs / reel.

2. Taping form and dimensions

Unit:mm



1. Carrier tape

2. Cover tape

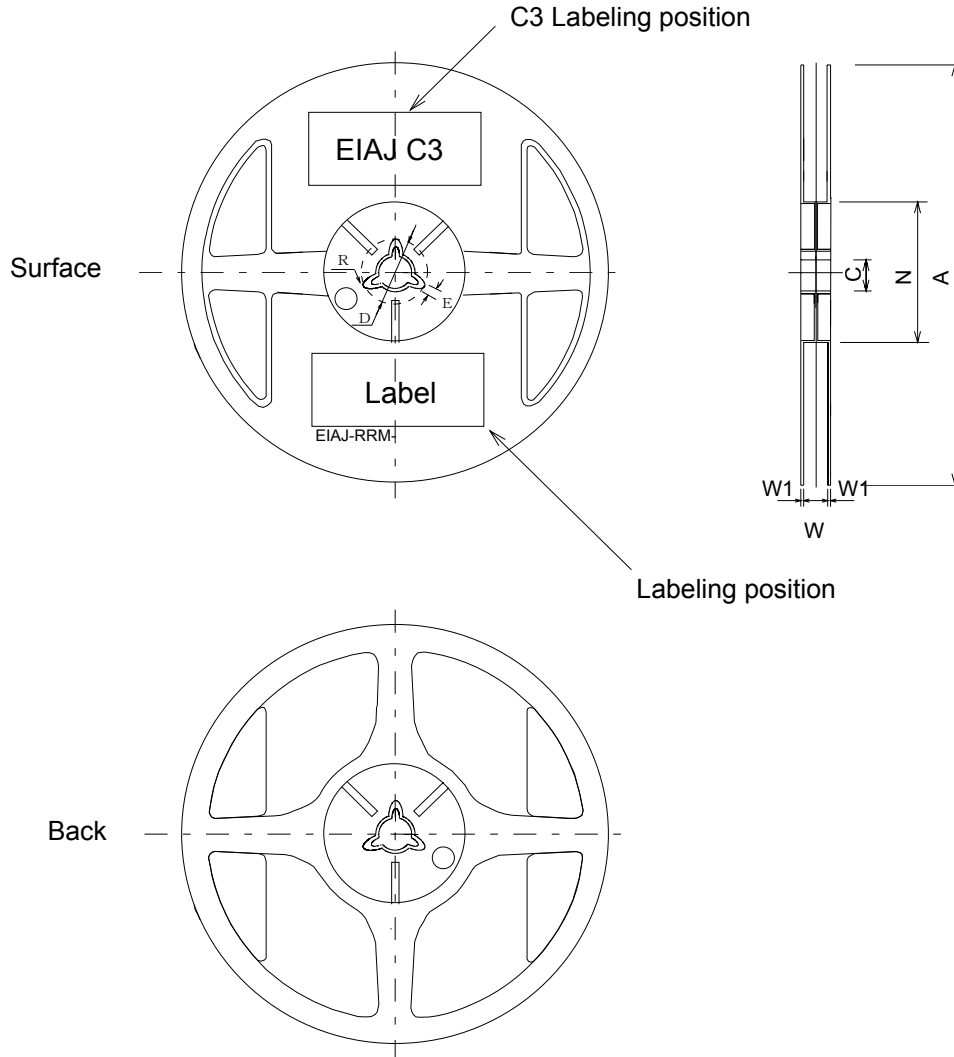
Item	Symbol	Dimensions	Remarks	
Dented square hole for product insertion	Length	A0	0.40±0.05	
		A1	1.30 <sup>+0.05</sup> <sub>-0.04</sub>	
	Width	B0	1.15±0.05	
		B1	1.40±0.05	
	Depth	K	0.60 <sup>+0.05</sup> <sub>-0.04</sub>	
	Lead position depth	K2	0.65 <sup>+0.05</sup> <sub>-0.04</sub>	
Pitch	P1	2.00±0.05	Accumulated error ±0.2max/10 pitches	
Sprocket hole	Diameter	D0	1.55±0.05	
	Pitch	P0	4.00±0.06	Accumulated error ±0.2max/10 pitches
	Position	E	1.75±0.06	
Center-to-center distance	Longitudinal	P2	2.00±0.05	
	Traverse	F	3.50±0.05	
Cover tape	Width	W1	5.4±0.1	
Carrier tape	Width	W	8.0±0.2	
	Thickness	t1	0.2±0.1	
Hole outer depth	K1	0.70±0.10		
Total thickness	t2	0.80±0.20		

Note : 1) Radius at each corner shall be 0.25R or less.

<b>Reference</b>	<b>Tape and reel information</b>	SSSMini3-F2-B	
		Total pages	page
		2	2

3. Reel and dimensions

Unit:mm



Item		Symbol	Dimensions	Remarks	
Flange	Diameter	A	180+0.0/-3.0		
	Thickness	W1	1.2		
	Distance between flanges	W	9.0±0.3		
Hub	Outer diameter	N	60.0+1.0/-0.0		
	Spindle hole diameter	C	13.0±0.2		
	Keyway	Width	E	2.0±0.5	
		Depth	D	21.0±0.8	
	Radius at corner	R	1.0		
Indication of the name, etc		To be printed on one side of flange. Name, Quantity, Serial No, etc. to be shown			

## Request for your special attention and precautions in using the technical information and semiconductors described in this book

- (1) If any of the products or technical information described in this book is to be exported or provided to non-residents, the laws and regulations of the exporting country, especially, those with regard to security export control, must be observed.
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- (3) The products described in this book are intended to be used for general applications (such as office equipment, communications equipment, measuring instruments and household appliances), or for specific applications as expressly stated in this book.  
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Even when the products are used within the guaranteed values, take into the consideration of incidence of break down and failure mode, possible to occur to semiconductor products. Measures on the systems such as redundant design, arresting the spread of fire or preventing glitch are recommended in order to prevent physical injury, fire, social damages, for example, by using the products.
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